



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

0755-83047638

ysbdt@szyoushang.cn

www.szyoushang.cn



企业微信二维码



企业QQ二维码

Product Summary

$V_{(BR)DSS}$	Max $R_{DS(ON)}$	Max I_D $T_A = +25^{\circ}C$
30V	0.050Ω @ $V_{GS} = 10V$	4.6A

Description and Applications

This new generation of TRENCH MOSFET from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.

- DC - DC converters
- Power Management Functions
- Disconnect Switches
- Motor Control

Features and Benefits

- Low On-resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive

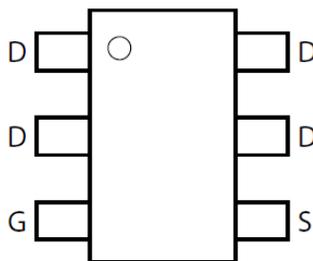
Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 Ⓜ3
- Weight: 0.015 grams (Approximate)

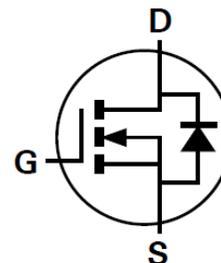
SOT26



Top View



Pinout Top-view



Device Symbol

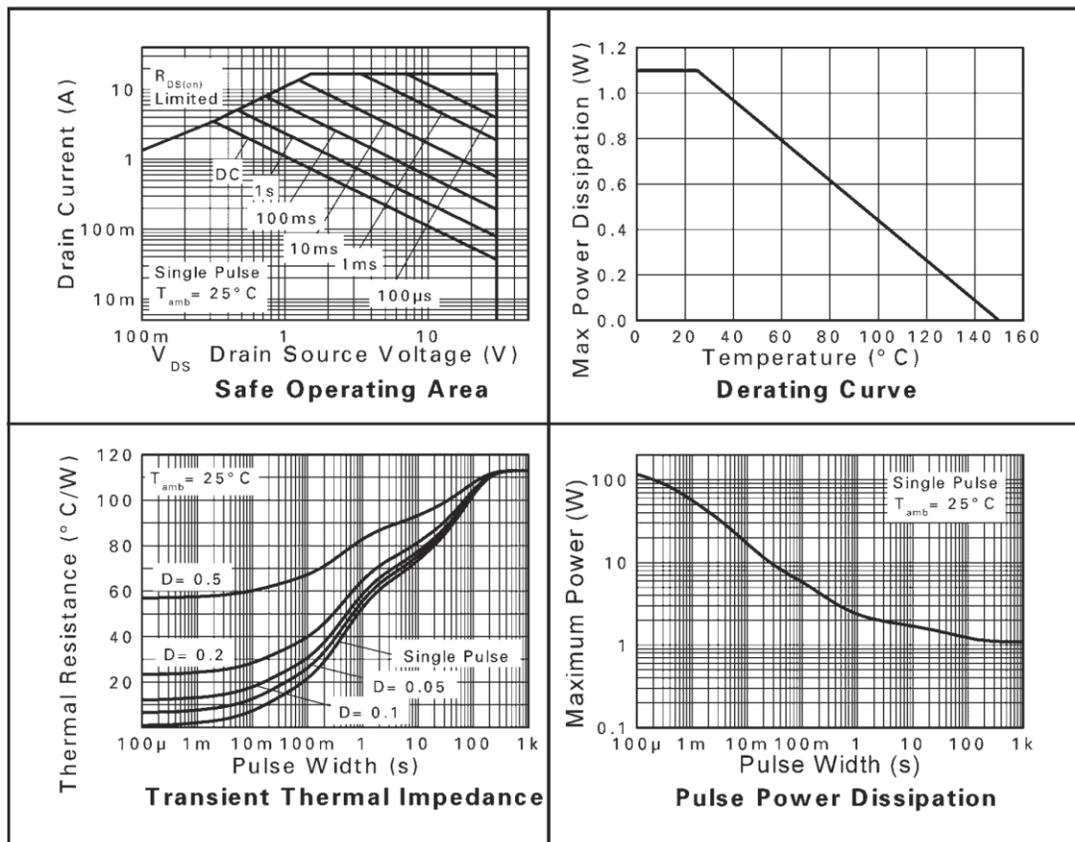
Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DS}	30	V
Gate-Source Voltage			V_{GS}	± 20	V
Continuous Drain Current	$V_{GS} = 10\text{V}$	$T_A = +25^\circ\text{C}$ (Note 6)	I_D	4.6	A
		$T_A = +70^\circ\text{C}$ (Note 6)		3.7	
		$T_A = +25^\circ\text{C}$ (Note 5)		3.7	
Pulsed Drain Current (Note 7)			I_{DM}	17	A
Continuous Source Current (Body Diode) (Note 6)			I_S	2.6	A
Pulsed Source Current (Body Diode) (Note 7)			I_{SM}	17	A

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation at $T_A = +25^\circ\text{C}$ (Note 5)	P_D	1.1	W
Linear derating factor (Note 5)		8.8	mW/ $^\circ\text{C}$
Power Dissipation at $T_A = +25^\circ\text{C}$ (Note 6)	P_D	1.7	W
Linear derating factor (Note 6)		13.6	mW/ $^\circ\text{C}$
Junction to Ambient (Note 5)	$R_{\theta JA}$	113	$^\circ\text{C/W}$
Junction to Ambient (Note 6)	$R_{\theta JA}$	73	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_{L}, T_{STG}	-55 to +150	$^\circ\text{C}$

- Notes:
- For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
 - For a device surface mounted on FR-4 PCB measured at $t \leq 10$ secs.
 - Repetitive rating 25mm x 25mm FR-4 PCB, $D = 0.05$, pulse width 10 μs - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.

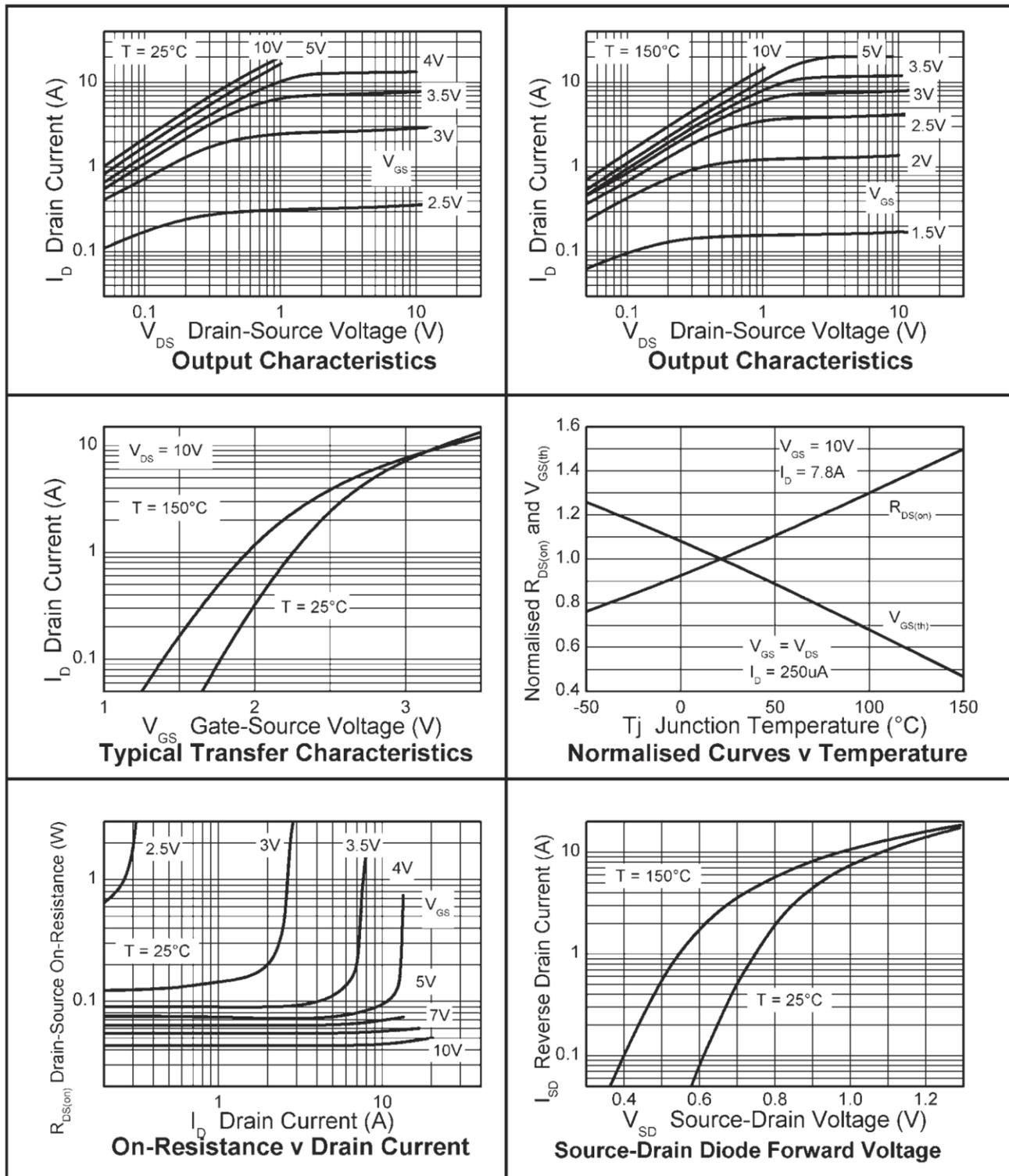
Thermal Characteristics


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

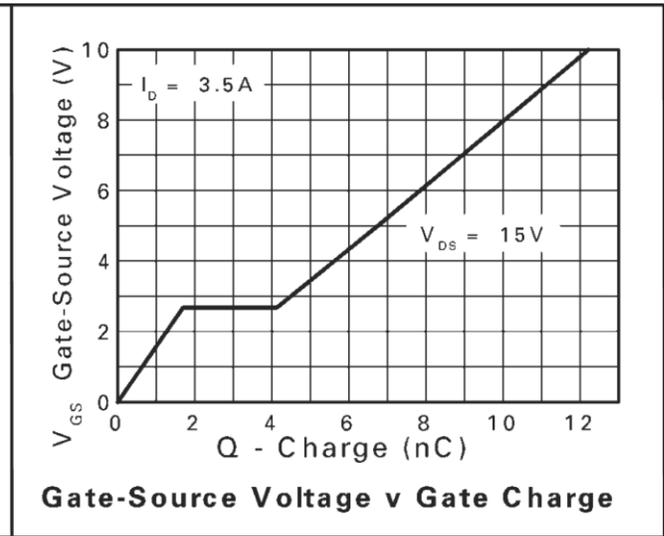
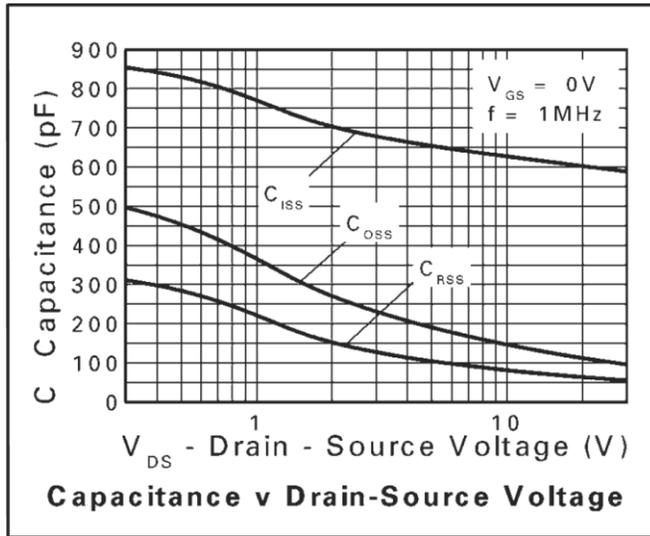
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-source Breakdown Voltage	BV _{DSS}	30	—	—	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	0.5	μA	V _{DS} = 30V, V _{GS} = 0V
Gate-body Leakage	I _{GSS}	—	—	100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS						
Gate-source Threshold Voltage	V _{GS(th)}	1	—	—	V	I _D = 250μA, V _{DS} = V _{GS}
Static Drain-source On-state Resistance (Note 8)	R _{DS(on)}	—	—	0.050	Ω	V _{GS} = 10V, I _D = 7.8A
				0.065		V _{GS} = 4.5V, I _D = 6.8A
Forward Transconductance (Notes 8 & 10)	g _{fs}	—	10	—	S	V _{DS} = 10V, I _D = 7.8A
Diode Forward Voltage (Note 8)	V _{SD}	—	0.85	0.95	V	T _J = +25°C, I _S = 3.2A, V _{GS} = 0V
DYNAMIC CHARACTERISTICS (Notes 9 & 10)						
Input Capacitance	C _{iss}	—	600	—	pF	V _{DS} = 25V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{oss}	—	104	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	58.5	—	pF	
Gate Charge	Q _g	—	6.9	—	nC	V _{GS} = 5V, V _{DS} = 15V I _D = 3.5A
Total Gate Charge	Q _g	—	12.6	—	nC	V _{GS} = 10V, V _{DS} = 15V I _D = 3.5A
Gate-source Charge	Q _{gs}	—	2.0	—	nC	
Gate-drain Charge	Q _{gd}	—	2.0	—	nC	
Reverse Recovery Time (Note 10)	t _{rr}	—	18.8	—	ns	T _J = +25°C, I _F = 3.5A, di/dt = 100A/μs
Reverse Recovery Charge (Note 10)	Q _{rr}	—	14.1	—	nC	
Turn-on Delay Time	t _{d(on)}	—	2.9	—	ns	V _{DD} = 15V, V _{GS} = 10V I _D = 3.5A, R _G = 6.0Ω
Turn-on Rise Time	t _r	—	6.4	—	ns	
Turn-off Delay Time	t _{d(off)}	—	16.0	—	ns	
Turn-off Fall Time	t _f	—	11.2	—	ns	

- Notes:
8. Measured under pulsed conditions. Width=300μs. Duty cycle ≤ 2%.
 9. Switching characteristics are independent of operating junction temperature.
 10. For design aid only, not subject to production testing.

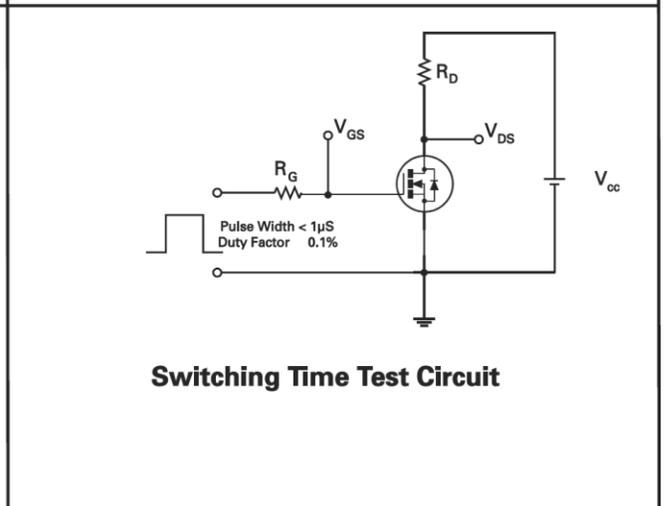
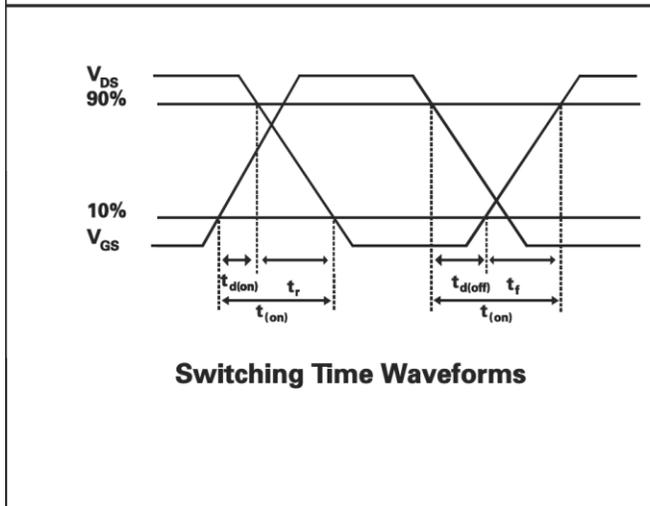
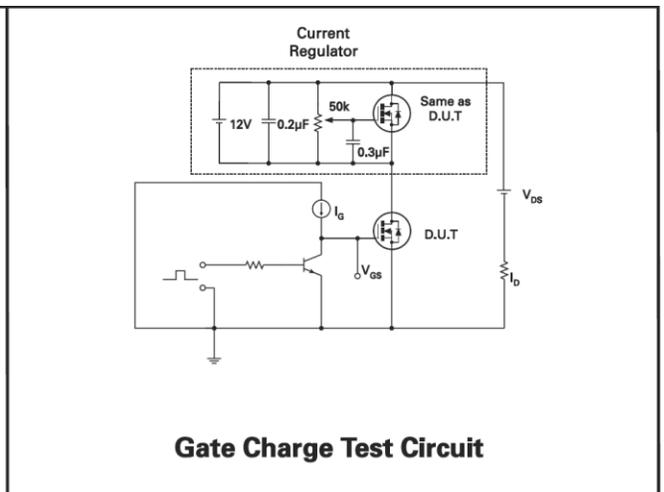
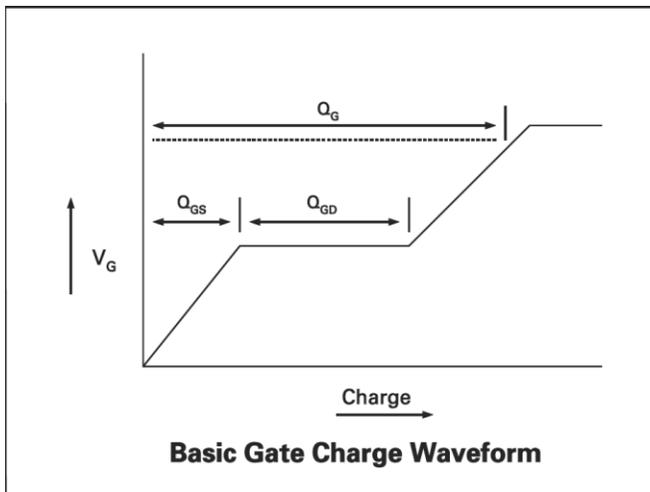
Typical Characteristics



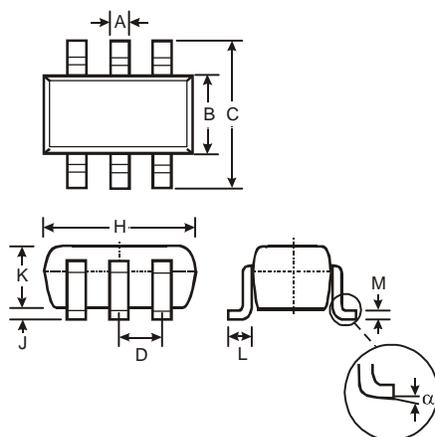
Typical Characteristics (Cont.)



Test Circuits

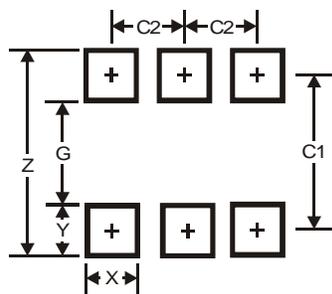


Package Outline Dimensions



SOT26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95